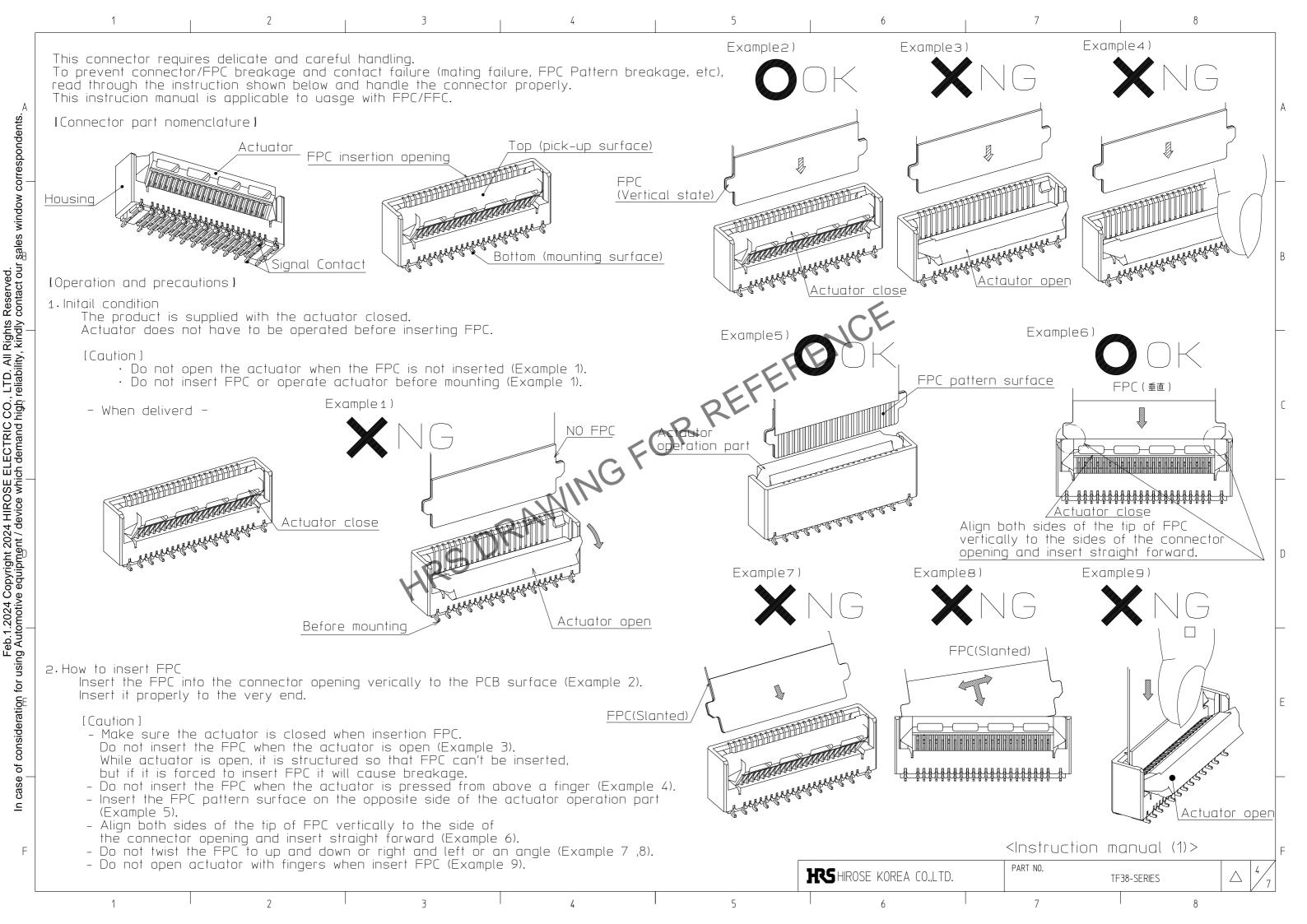
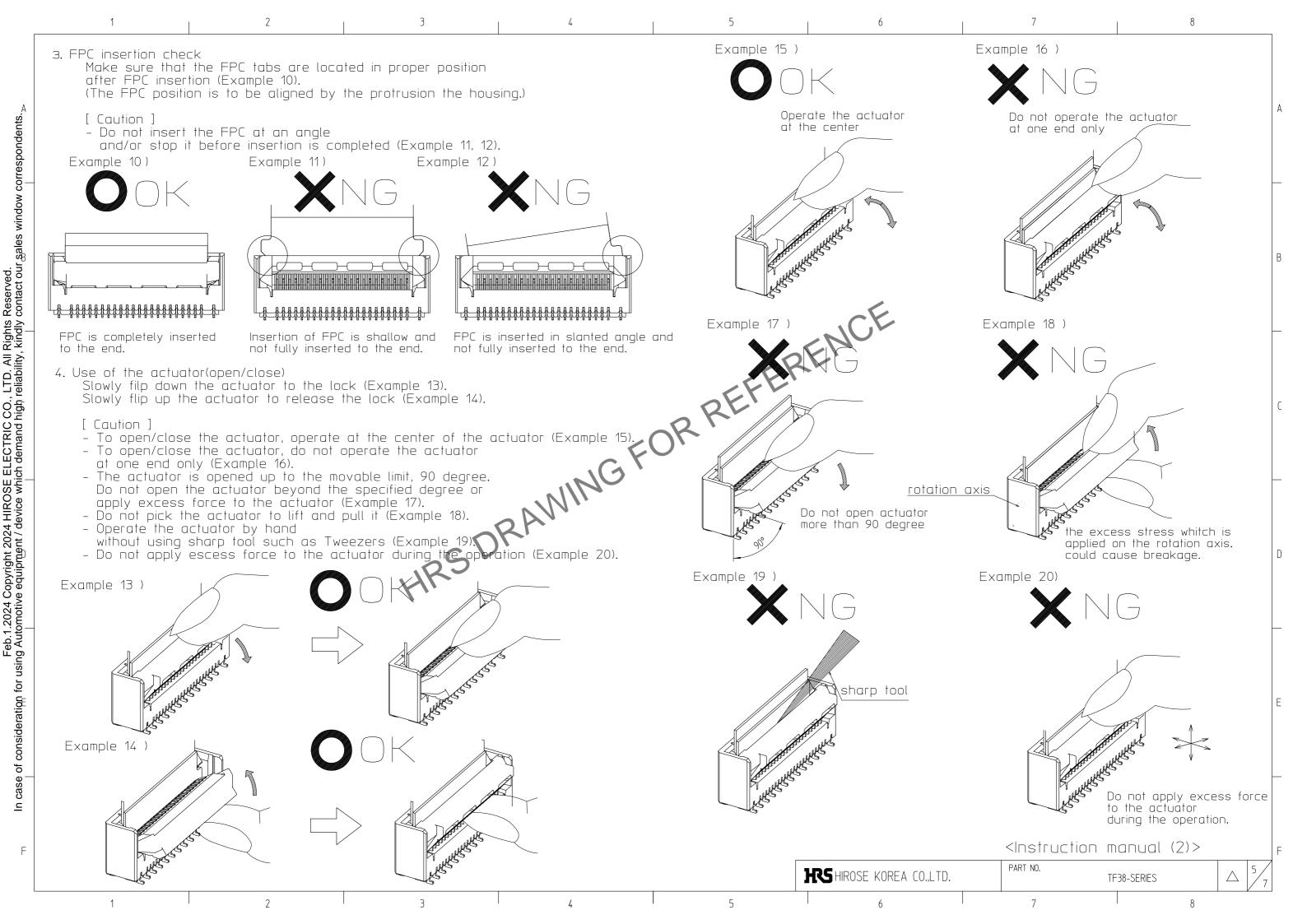
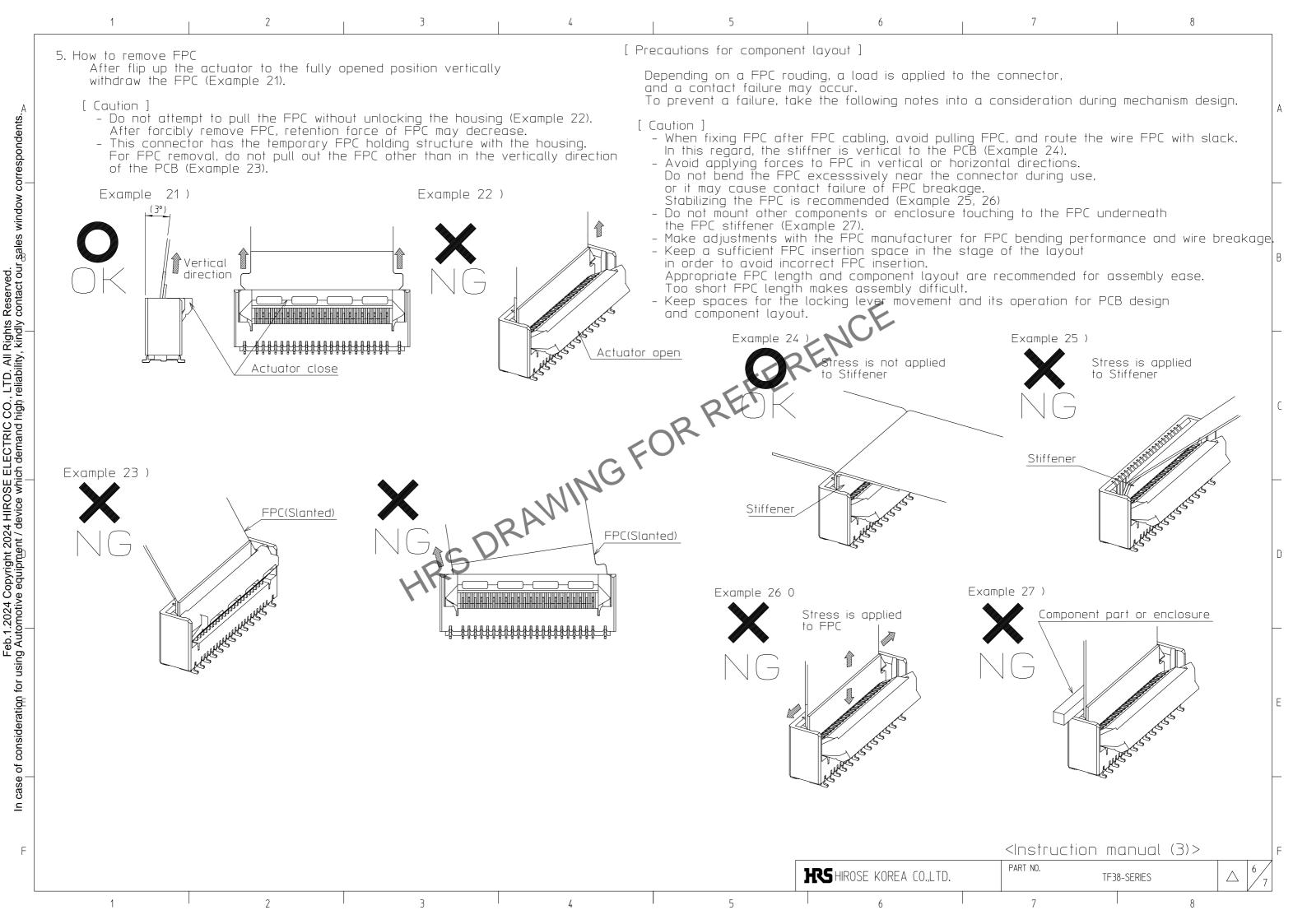
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								<u>2</u> 1	RE-5-2133			K.G.B C.D.H 19. C.Y.H C.D.H 23.	03 . 29 🛆					
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	PART NUMBER	NUMBER OF CONTACTS	DIMENSION OF CONNECTOR, FPC/FFC, PCB PATTERN						DIMENSION OF									
-	110110211		В	(D	E	F	G	H	J	K	L	M					
2	TF38-16S-0.5SV(830)	16	8.57	11.2	7.5	9.5	8.5	10	24	_	11.5	11.5	24.5					
	TF38-18S-0.5SV(830)	18	9.57	12.2	8.5	10.5	9.5	11	24	_	11.5	12.5	24.5					
	TF38-20S-0.5SV(830)	20	10.57	13.2	9.5	11.5	10.5	12	24	_	11.5	13.5	24.5					
	TF38-22S-0.5SV(830)	22	11.57	14.2	10.5	12.5	11.5	13	24	-	115	14.5	24.5					
	TF38-24S-0.5SV(830)	24	12.57	15.2	11.5	13.5	12.5	14	24	25	11.5	15.5	24.5					
	TF38-26S-0,5SV(830)	26	13.57	16.2	12.5	14.5	13.5	15	32	28.4	14.2	16.5	32.5					
	TF38-30S-0.5SV(830)	30	15.57	18.2	14.5	16.5	15.5	1/1	32	28.4	14.2	18.5	32.5					
	TF38-32S-0.5SV(830)	32	16.57	19.2	15.5	175	16.5	18	44	40.4	20.2	19.5	44.5					
	TF38-36S-0.5SV(830)	36	18.57	21.2	17.5	19.5	18.5	20	44	40.4	20.2	21.5	44.5					
	TF38-38S-0.5SV(830)	38	19.57	222	18.5	20.5	19.5	21	44	40.4	20.2	22.5	44.5					
	TF38-40S-0.5SV(830)	40	20.57	23.2	19.5	21.5	20.5	22	44	40.4	20.2	23.5	44.5					
	TF38-45S-0.5SV(830)	45	23.07	25.7	22	24	23	24.5	44	40.4	20.2	26	44.5					
	TF38-50S-0.5SV(830)	50	25.57	28.2	24.5	26.5	25.5	27	44	40.4	20.2	28.5	44.5					
	TF38-60S-0.5SV(830)	60	30.57	33.2	29.5	31.5	30.5	32	56	52.4	26.2	33.5	56.5					
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								NO.	MATER		ENIO	DEMINIO.	110	MATERIAL	EMICH	DEMARKS		
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								CODE	CODE NO. (OLD) DRAW			RAWING NO. EDC3-632306-80		DADT NO	TF38-**S-0.5SV(8		<u> </u>	
									1:1 UNITS		HS HIROSE KOREA CO.,LTD.		CODE NO. CL 6537-0017-0-830			3/7		
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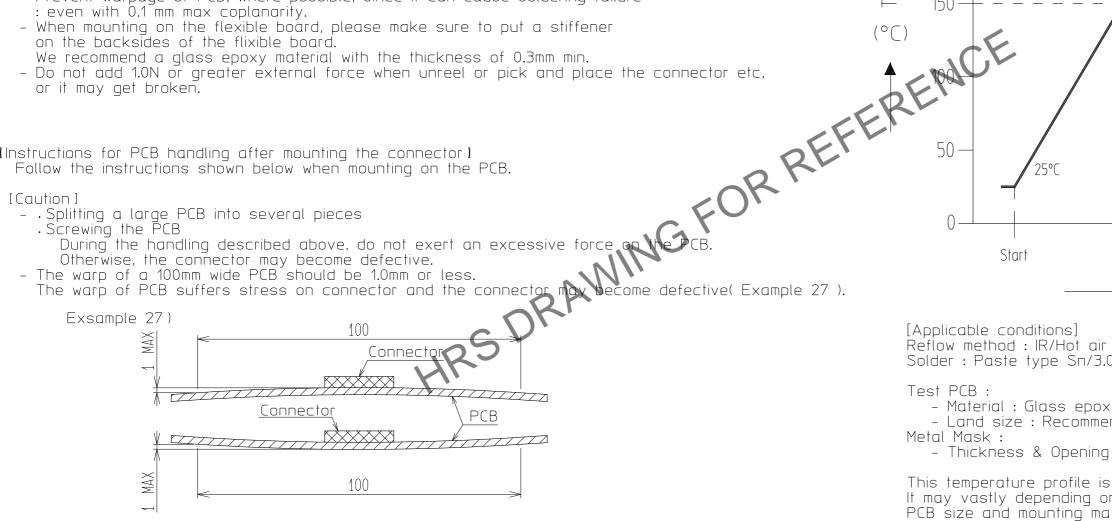




Instructions for mouting on the PCB1 Follow the instructions shown below when mounting on the PCB.

- Refer to recommended layouts on the page 1 for PCB and Stencil pattern.
- Shorter pattern width than the recommended PCB dimension, could cause solder wicking and/of flux penetration.
- Larger pattern than the recommended stencil dimension, could cause solder wicking and/or flux penetration.
- Clearence underneath the contact lead and the housing is very small. In case solder resist and/or silk screening are applied on PCB underneath the connector. verify the thickness, or it could push up the connector bottom and may cause soldering defect and/or insufficient fillet formation.
- Apply reflow temperature profile within the specified conditions. In individual applications, the actual temperature may vary. depending on solder paste type, volume/thickness and PCB size/thickness. Consult your solder paste and equipment manufacturer for specific recommendations.
- Prevent warpage of PCB, where possible, since it can cause soldering failure : even with 0.1 mm max coplanarity.
- When mounting on the flexible board, please make sure to put a stiffener

Instructions for PCB handling after mounting the connector I

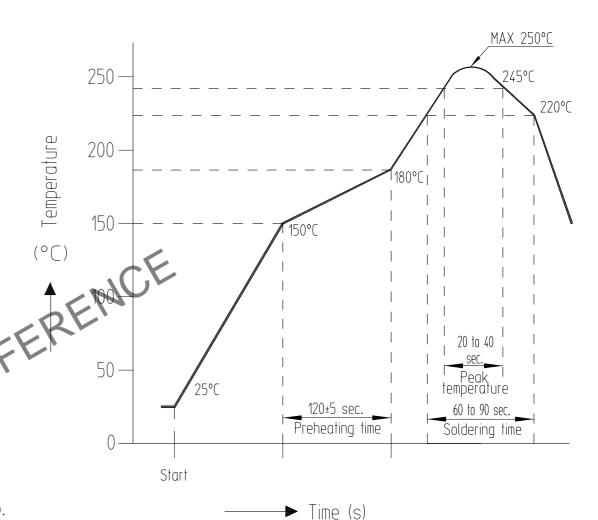


Instructions on manual soldering I

Follow the instructions shown below when soldering the connector manually during repair work, etc.

- Do not perform manual soldering with the FPC inserted into the connector.
- Do not heat the connector excessively. Be very careful not to let the soldering iron contact any parts other than connector leads. Otherwise, the connector may be deformed or melt.
- Do not supply excessive solder (or flux). If excessive solder (or flux) is supplied on the terminals, solder or flux may adhere to the contacts, resulting in poor contact. Supplying excessive solder to the metal fittings may hinder locking lever rotation, resulting in breakage of the connector.

IRecommended reflow temperatur profile I



Solder : Paste type Sn/3.0Ag/0.5Cu

- Material : Glass epoxy
- Land size : Recommended Pattern

- Thickness & Opening size : Recommended Pattern

This temperature profile is based on the above conditions. It may vastly depending on solder paste type, manufacturer, PCB size and mounting materials. Please use only after checking the mounting conditions.

<Instruction manual (4)>

HSHIROSE KOREA CO.,LTD.

PART NO. TF38-SERIES

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